# TOIREX

# XP202A0003MR-G

ETR1128-003

### P-channel 4V (G-S) MOSFET

### **FEATURES**

- Low On Resistance
- Ultra High Speed Switching
- 4V Driving
- •EU RoHS Compliant, Pb Free

### **APPLICATIONS**

Switching

### PRODUCT NAME

PRODUCT NAME	PACKAGE	ORDER UNIT	
XP202A0003MR-G	SOT-23	3,000/Reel	

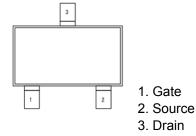
The "-G" suffix indicates that the products are Halogen and Antimony free as well as being fully RoHS compliant.

### ABSOLUTE MAXIMUM RATINGS

PARMETER	SYMBOL	RATINGS	UNITS
Drain-Source Voltage	$V_{\text{DSS}}$	-30	V
Gate-Source Voltage	$V_{GSS}$	±20	٧
Drain Current (DC)	$I_D$	-3	Α
Drain Current(Pulse)(* 1)	I <sub>DP</sub>	-12	Α
Channel Power Dissipation (*2)	Pd	1	W
Channel Temperature	Tch	+150	
Storage Temperature	Tstg	- 55 ~ +150	

 $<sup>^{(\</sup>star^1)}$ PW 10  $\mu$  s,duty cycle 1%

### PIN CONFIGURATION



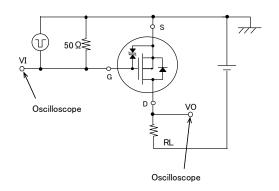
SOT-23(TOP VIEW)

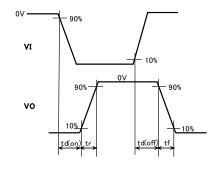
### **ELECTRICAL CHARACTERISTICS**

PARAMETER	CVMDOL	TEST CONDITIONS		LIMITS		LIMITO
PARAMETER	SYMBOL TEST CONDITIONS		MIN.	TYP.	MAX. UNITS	
Drain-Source Breakdown Voltage	Breakdown Voltage V <sub>(BR)DSS</sub> I <sub>D</sub> =-1mA, V <sub>G</sub>		-30	-	-	V
Drain-Source Cut-Off Current	I <sub>DSS</sub>	V <sub>DS</sub> =-30V, V <sub>GS</sub> =0V	ı	-	-1	μΑ
Gate-Source Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±16V,VDS=0V	-	-	±10	μΑ
Gate-Source Cut-Off Voltage	$V_{GS(off)}$	V <sub>DS</sub> =-10V,ID=-1mA	-1.2	-	-2.6	V
Forward Transfer Admittance	yfs	V <sub>DS</sub> =-10V,ID=-3A	ı	8.0	-	S
	R <sub>DS(ON)</sub> 1	I <sub>D</sub> =-1.5A,VGS=-10V	-	45	-	mΩ
Drain-Source ON Resistance	R <sub>DS(ON)</sub> 2	I <sub>D</sub> =-1.0A,VGS=-4.5V	-	67	-	mΩ
	R <sub>DS(ON)</sub> 3	I <sub>D</sub> =-1.0A,VGS=-4V	-	76	-	mΩ
Input Capacity	Ciss	V <sub>DS</sub> =-10V,f=1MHz	-	435	-	pF
Output Capacity	Coss	V <sub>DS</sub> =-10V,f=1MHz	-	110	-	pF
Feedback capacity	Crss	V <sub>DS</sub> =-10V,f=1MHz	-	85	-	pF
Turn on Delay time	td(on)	I <sub>D</sub> =-1A	-	6	-	ns
Rise Time	tr	I <sub>D</sub> =-1A	-	12	-	ns
Turn off Delay Time	td(off)	I <sub>D</sub> =-1A	-	28	-	ns
Fall Time	tf	I <sub>D</sub> =-1A	-	10	-	ns
All Gate Charge Amount Qg		V <sub>DS</sub> =-15V, V <sub>GS</sub> =-10V, I <sub>D</sub> =-3A	-	10	-	nC
Gate Source Charge Amount	Qgs	V <sub>DS</sub> =-15V, V <sub>GS</sub> =-10V, I <sub>D</sub> =-3A	-	1.2	-	nC
Gate Drain Charge Amount	Qgd	V <sub>DS</sub> =-15V, V <sub>GS</sub> =-10V, I <sub>D</sub> =-3A	-	2.2	-	nC
Diode Forward Voltage	V <sub>SD</sub>	I <sub>S</sub> =-3A, V <sub>GS</sub> =0V	-	-0.8	-1.2	V

<sup>(\*2)</sup>Ceramic Board (900mm2 × 0.8mm) Mounting

## SWITCHING-TIME TEST CIRCUIT

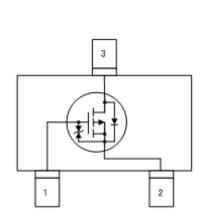


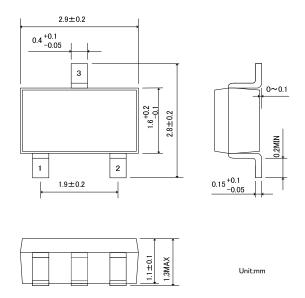


# **EQUIVALENT CIRCUIT**

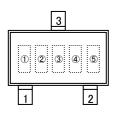
## PACKAGING INFORMATION

SOT-23





# **MARKING RULE**



#### represents product series

MARK	PRODUCT SERIES
6	XP202*****-G

#### represents product group and number

roproce	nto product §	group and name	701	
MARK		PRODUCT	PRODUCT	PRODUCT SERIES
		GROUP	NUMBER	11100001 0211120
A D		00	03	XP202A0003**-G

, represents production lot number

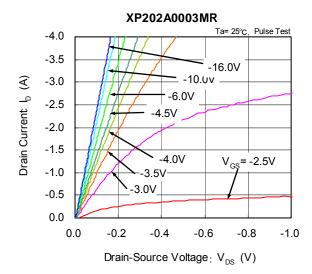
01 to 09, 0A to 0Z, 11 to 9Z, A1 to A9, AA to Z9, ZA to ZZ repeated (G,

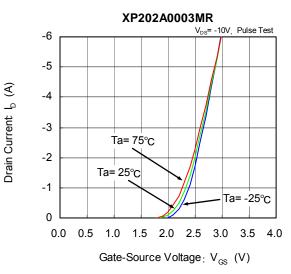
I, J, O, Q, W excluded)

### TYPICAL PERFORMANCE CHARACTERISTICS

(1) Drain Current vs. Drain-Source Voltage

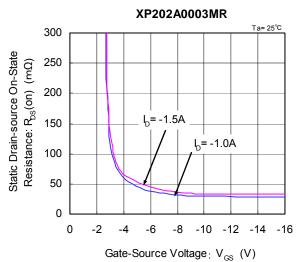
(2) Drain Current vs. Drain-Source Voltage

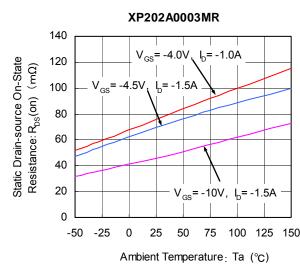




(3) Drain-Source On-State Resistance vs. Gate-Source Voltage

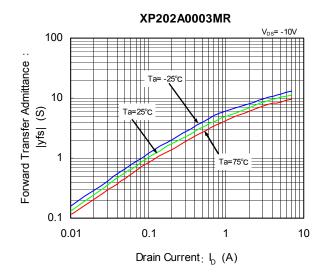
(4) Drain-Source On-State Resistance vs. Ambient Temperature

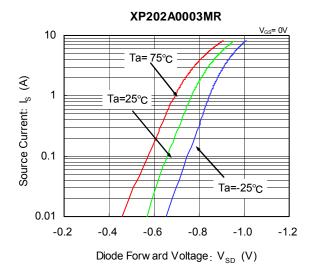




(5) Forward Transfer Admittance vs. Drain Current

(6) Source Current vs. Diode Forward Voltage

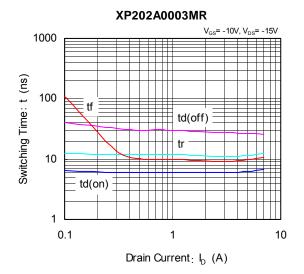




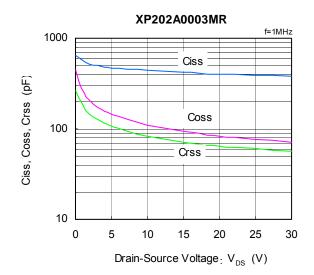
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### TYPICAL PERFORMANCE CHARACTERISTICS

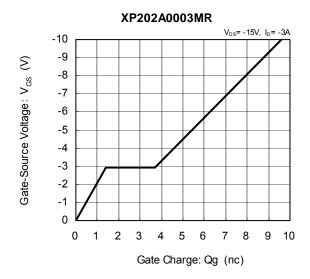
(7) Switching Time vs. Drain Current



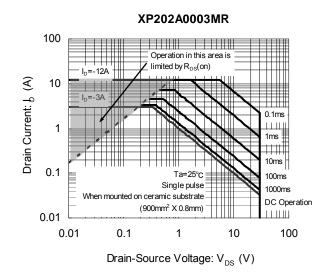
(8) Ciss, Coss, Crss vs. Drain-Source Voltage



(9) Gate-Source Voltage vs. Gate Charge



(10) Area of Safe Operation



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